

# MECHANICAL CASE OUTLINE

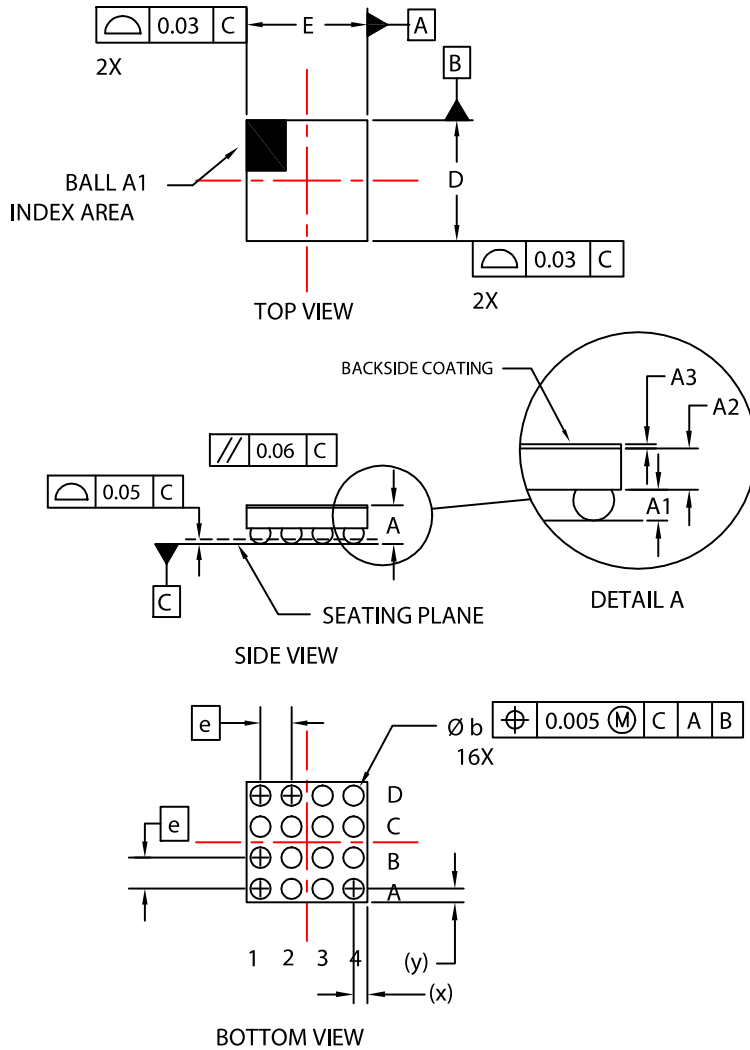
## PACKAGE DIMENSIONS

ON Semiconductor®



**WLCSP16 1.52x1.52x0.432**  
CASE 567ZM  
ISSUE O

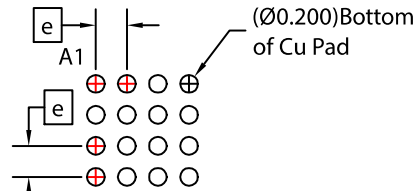
DATE 14 SEP 2020



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.391	0.432	0.473
A1	0.154	0.174	0.194
A2	0.215	0.233	0.251
A3	0.022	0.025	0.028
b	0.211	0.231	0.251
D	1.49	1.52	1.55
E	1.49	1.52	1.55
e	0.35 BSC		
x	0.220	0.235	0.250
y	0.220	0.235	0.250



**RECOMMENDED MOUNTING FOOTPRINT\* (NSMD PAD TYPE)**

\*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>WLCSP16 1.52x1.52x0.432</b>	<b>PAGE 1 OF 1</b>

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